

# Hermetic Seam Sealing Microelectronic Devices

Date	Title/Topic
December 2018	Resistance Weld Monitoring for Improved Throughput and Quality
June 2019	Laser Source Selection for Micro-welding
September 2019	Hermetic Seam Sealing Microelectronic Packages
November 2019	Laser Weld Monitoring
February 2020	Resistance Spot Welding - Weld Head Selection

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## HERMETIC SEAM WELDING PROCESS SUCCESS



- Package Design
- Plating
- Material Composition
- Package Geometry





# **E** EQUIPMENT

- Seam Welder
- Projection Welder
- Electrode and Fixture Design









- Weld Schedule
- Oven Bakeout Schedule
- Dry Environment Schedule







## **COMPANY OVERVIEW**

#### Amada Weld Tech

Established as the Weldmatic Division of Unitek Corporation in 1948. In 2001 acquired BENCHMARK International Inc. a world leader in manufacturing hermetic sealing systems. AMADA WELD TECH has been a pioneer in the design and manufacture of welding, marking, cutting, hermetic sealing and bonding systems for more than 70 years!



- A subsidiary of Amada Miyachi, Co. Ltd.
- A subsidiary of AMADA HOLDINGS CO., LTD.
- Headquartered in Monrovia, California USA
- Quality
  - Company: ISO 9001 Certified
  - Equipment: CE, CDRH, CCC, NFPA79, CSA Certified

#### Past Branding – Hermetic Sealing Product Lines



#### **Core Technologies**



#### **Industries Served**

Medical | Automotive | Battery | Electronics | Military | Aerospace | Data Communication Photonics | Life Sciences and many more!

## AMADA WELD TECH - GLOBAL FAMILY OF COMPANIES



## HERMETIC SEAM WELDING OF MICRO ELECTRONIC PACKAGES

- Introduction Basics
  - What is hermetic seam welding?
  - Parallel gap seam welding
  - Opposed electrode projection seam welding
- · Hermetic sealing in controlled dry environment
- Hermetic seal testing
- What can go wrong with your process?
- · Future of hermetic sealing products
- Summary









## **INTRODUCTION - BASICS: PRINCIPLES OF HERMETIC SEALING**

**The Objective:** Protecting and controlling the internal conditions of the implantable medical and sensitive electronic devices from harsh or challenging environmental conditions

**The Solution:** Hermetic Sealing. Encapsulation of the device into an air tight metal or ceramic housing.

**The Technology:** This can be realized by joining a metal lid or cap to a metal or a ceramic base package which contains the electronic device using either parallel gap seam welding or opposed electrode projection resistance welding technologies.



Parallel gap seam welding and opposed electrode projection resistance welding technologies



Parallel Gap Seam Welding

**Opposed Electrode Projection Welding** 

# INTRODUCTION - BASICS: PRINCIPLES OF PARALLEL GAP SEAM WELDING

A seam welder is intended to deliver multiple overlapping weld spots creating a continuous weld joining a metal lid to a metal or a ceramic package which contains an electronic device.



#### (M) Materials: Part design metal tub packages and material

IMPORTANT: Preferred material is Kovar and maintain lid thickness at .004" (100 µm)

#### **Lid Design Guidelines**

Flat lid -  $.004'' \pm .001''$  thick (100 µm ±25 µm)

Step lid – Major thickness >= .010'' (250 µm)

Perimeter flange thickness .004"  $\pm$  .001 (100 µm  $\pm$ 25 µm)



Metal to glass seal feedthrough connection

#### Metal tub base design guidelines

**Kovar** is the preferred package material having similar CTE (Coefficient of Thermal Expansion) as glass preventing metal to glass seals from leaking due material expansion from heat generated in the welding process





Hairline glass fracture due to mechanical or thermal stress

M) Materials: Ceramic package seal ring and lid design, plating

**IMPORTANT:** Lid should never be larger than the seal ring

#### **Lid Design Guidelines**

Flat lid - .004"  $\pm$  .001" thick (100  $\mu m$   $\pm 25$   $\mu m)$ 

Step lid – Major thickness >= .010'' (250 µm)

Perimeter flange thickness .004"  $\pm$  .001 (100  $\mu$ m  $\pm$ 25  $\mu$ m)



#### Lid to seal ring perimeter clearance:

 $.003"\pm .001"$  (75 mm  $\pm 25$  mm) to prevent lids from overhanging

#### Lid perimeter flange thickness:

.004" ± .001 (100 μm ±25 μm)

Thin lids require low heat to weld resulting to cooler packages, minimizes thermal stress preventing the ceramic base from cracking

Seal ring minimum height: .022" (559 µm)

Seal ring minimum width: .020" (500µm)

will provide sufficient area to weld and clearance between electrode's outer edge and top surface of the ceramic base

#### **Typical materials:**

Kovar, Nickel and Ceramic Base

#### **Typical plating:**

Nickel plating 50-100  $\mu$ -in (1.3  $\mu$ m – 2.5  $\mu$ m)

Gold plating  $20 - 50 \mu$ -in (0.5  $\mu$ m - 1.3  $\mu$ m)

Low to Medium Phosphorus Electroless Plating (1 - 9 %)



A misaligned lid is still within the seal ring



Lid overhanging

Gap between lid and seal ring caused by insufficient step clearance, the lid's step fillet radius is resting on top of the seal ring

Lid tip has a radius

Gap between lid and seal ring



Detail Packages with a corner radius will cosmetically look better, no overheated corners and less chances of arcing

Detail Sharp corners will may cause arcing and over heated corners



The key objective in resistance welding to efficiently generate heat while directing it to a specific predetermined location

#### General heat generation formula for resistance welding Heat = $I^2 \times R \times t - K$

#### Where:

- I = Weld current (Amperes)
- R = Resistance (Ohms)
- t = Weld time (seconds)

K= thermal factor due to: weld force, material properties, efficiency of current path, fixturing, heat sinking

Relation between welding force, weld current, area of contact, contact resistance, weld time, material properties, plating properties and heat generated during a welding process.

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- Resistive materials
- Higher weld current
- Longer weld time
- More weld spots delivered at a faster rate

More material mass

- More heat sinking
- Thicker and more conductive plating
- More force = Less resistance = Less heat



#### Process: Process – Weld schedule key parameters

• Lid Dimension • Weld Force • Spot Spacing • Overtravel • Weld Current • Weld Speed



#### Spot Spacing:





Cooler packages and no overheated corners are realized using slow speed position based firing and less weld spots at the corners of the package Typical weld settings for .004" (100  $\mu$ m) lids Weld Current: 0.30 – 0.45 kA Weld Pulse: 2 – 4 msec Weld Speed: 0.1 - 0.5 ips (2.5 – 12.7 mm/s) Spot Spacing: .008" (200  $\mu$ m) Overtravel: .020" (500  $\mu$ m) Weld Force: 1400 grams

### ) Process: Weld electrode tracking

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AUTO-TRACK FEATURE : Seam welder automatically increments 0.001"(25.4 µm) every weld pass



Electrode tracking prolongs life and even wear of electrode weld face

# E Equipment: BASIC and ADVANCED

When do you choose one over the other?



#### **BASIC Seam Welder**

- R & D and **Low volume** production 50 60 UPH (data from 10 mm<sup>2</sup> packages)
- Single part welding operation
- Rectangular and circular sealing applications
- Manual lid placement operation



#### **ADVANCED Seam Welder**

- **High volume** production, 150 to 180 UPH (data from 10 mm<sup>2</sup> packages)
- Multiple parts welding operation
- Rectangular sealing applications
- Automatic Vision assisted pick and place, tacking and seam sealing operation

**E** ADVANCED – Automatic pick place, tack and seam seal welding system



Vision assisted automatic pick and place and tacking



Pattern match using vision tool solves locating hard to find edges and a gold seal ring on gold background images by masking undesired background images

(E) Equipment: Seam welder, HF welding power supply, electrodes and fixture design



Seam welder

HF welding power supply



(P) Process: What can go wrong?

Electrode inner edge witness marks at the corner of the package





## P) Process: What can go wrong?

Unwelded corners due to insufficient weld travel



This can be resolved by welding beyond the lid size resulting to a weld overlap at the corners of the package

# Material: What can go wrong?

Lid to package corner radius mismatched design



## (M) Material: What can go wrong?

Tab protrusions at the lid perimeter edge



Before Seam Sealing

After Seam Sealing

## PARALLEL GAP SEAM WELDING Process: What can go wrong?

Insufficient weld spot overlap



## **INTRODUCTION - BASICS:**

#### Principles of Hermetic Sealing -

Parallel gap seam welding and opposed electrode projection welding technologies



Parallel gap seam welding



**Opposed electrode projection welding** 

This technology utilizes opposing electrodes joining a header containing the electronic device and covering it with a cap.



## Visual indicators of a successful weld

Weld fillet formation (typically seen when neither cap or header has a ring projection) At least 50 - 90% projection collapse ( a liner displacement can be added to the weld head)



Ρ

Fillet formation along the perimeter of the cap and header can be uses a visual indicator of a hermetic seal



Projection will collapse and will form a weld nugget or a solid state bond

a second

M Materials: Part design metal packages, electrodes and plating



## **DESIGN FEATURES:**

Projection located on either cap or header

- Cap position is constrained by the header within .001" - .003" (25.4 – 76.2 μm)
- Preferred material: Kovar
- Others materials: Nickel, Low carbon stainless steel, cold rolled steel

#### **Typical Plating:**

- Nickel 50-100 μ-in (1.3 2.5 μm)
- Gold  $20 50 \mu$ -in  $(0.5 1.3 \mu m)$





## **(E) WELDING APPROACH:**

Both cap and header are loaded at the bottom electrode

Materials: Part design metal packages, electrodes and plating



#### **DESIGN FEATURES:**

- E SOLUTION: Since the cap and header does not have a constraining feature with each other lower electrode design must have a feature to align the parts together using non-conductive dowel pins
- (M) Ring projection is on the cap
- Typical cap and header material: Kovar, nickel, cold rolled steel, low

carbon stainless steel

#### M Typical Plating:

Nickel 50-100  $\mu$ -in (1.3 - 2.5  $\mu$ m) Gold 20 - 50  $\mu$ -in (0.5 - 1.3  $\mu$ m)



Materials: Part design metal packages, electrodes and plating



#### **DESIGN FEATURES:**

- E SOLUTION: Since the cap and header does not have a constraining feature with each other lower electrode design must have a feature to align the parts together using non-conductive alignment disk
- W Typical cap and header material: Kovar, nickel, cold rolled steel, low carbon stainless steel

#### M Plating:

Nickel 50-100  $\mu$ -in (1.3 - 2.5  $\mu$ m) Gold 20 - 50  $\mu$ -in (0.5 - 1.3  $\mu$ m)





Process – Weld Schedule Development

TYPICAL ELECTRONIC DEVICES AND CAPACITOR DISCHARGE POWER SUPPLIES IN THE MARKET													
DEVICE TYPE	T0-56	T0-18	T0-46	T0-5	T0-39	T0-37	T0-8	T0-66	T0-3	14 DIP	24 DIP	RELAYS	HYBRIDS
PROJECTION	0.49"	0.7"	0.7"	1"	1"	1.1"	1.6"	1.9"	2.8"	2.4"	3.3"	4"	5"
LINEAR LENGTH (mm)	(12.5)	(17.8)	(17.8)	(25.4)	(25.4)	(27.2)	(40.6)	(48.3)	(71.1)	(61.0)	(83.8)	(101.6)	(127.0)
CD POWER SUPPLY													
MAXIMUM OUTPUT													
1000 JOULES	Х	Х	Х	Х	Х	Х							
3000 JOULES		Х	Х	Х	Х	Х	Х	Х					
6000 JOULES			Х	Х	Х	Х	Х	Х	Х	Х			
9000 JOULES				Х	Х	Х	Х	Х	Х	Х	Х	Х	
12000 JOULES				Х	Х	Х	Х	Х	Х	Х	Х	Х	Х

LEGEND: "X" - WELDABLE

## **P** BASELINE SETTINGS

#### **Clamping Speed:**

Slowest approach speed to prevent top electrode from damaging on to the device

#### Weld Force:

Round caps - 400 lb-F / inch (7.2 kg-F/mm) of projection

Rectangular caps – 700 lb-F / inch (12.5 kg-F/mm) of projection

#### Weld energy:

Round caps: 600 Joules/ inch (23.6 Joules/mm) of projection

Rectangular caps: 1000Joules / inch (39.4 joules/mm) of projection

Note: Recommended baseline setting will need further optimization.



WELD FORCE	WELD POWER	WELD TIME	CONTACT AREA	MATERIAL CONDUCTIVITY	CONTACT RESISTANCE	HEAT GENERATED
↔					-₽-	-₽-
	☆					☆
		ᢙ				ᠿ
			ᢙ		-₽-	-₽-
				☆		₽
					☆	☆

LEGEND: 🔶 - CAUSE 🛛 🕂 - EFFECT

## **OPPOSED ELECTRODE SEAM WELDING**

**E** Equipment: Projection Welding Systems



Projection Welding Systems 200 – 4000 lb-F (90.7 – 1,814 kg-F)



Projection welder with vacuum - backfill feature





Desktop projection welder with weld monitor

## **OPPOSED ELECTRODE SEAM WELDING**



(M) Materials – What can go wrong?

Projection Flatness issue will cause over welded joint at the high point of the projection and leaks at the low section of the projection.

Projection Flatness must be less than .002" (50µm)



Bowed cap flange will have the same welding issue with materials having a projection flatness issue. Overheated weld joint or material expulsion will be seen at the contact point of the cap to the header and leaks at sections with a gap.

Cap flange Flatness must be less than .002" (50µm)



Non-continuous projections will cause unwelded gaps resulting to a non-hermetic weld joint



Material Expulsion inside or outside the perimeter of the weld joint is a visual indicator of materials which have flatness issues, insufficient welding force, or excessive weld energy.

If expelled material is trapped in the package this will cause Particle Impact Noise Detection (PIND) test failure.





Equipment – What can go wrong?

#### Electrode design issue

Issue: Cap flange not seated flat in the lower electrode

**Solution:** Add a chamfer at the bottom electrode







## **RELIABILITY TESTING**

(P)

#### Process - Weld strength destructive testing

Objective - Mechanically separating welded lid or cap from base material

Visual indicators of a strong weld: 75 - 100% of the weld joint is still intact after mechanically separating the 2 welded parts



Testing weld strength - peel test



Mechanically separating cap from header





## HERMETIC SEALING CONTROLLED DRY ENVIRONMENT:



(E) Equipment – What is a glovebox purpose:

#### **Enclosure:**

· Maintains a controlled dry environment by monitoring desired moisture levels.

#### **Antechamber:**

- Door interlocking feature to prevent enclosure from being exposed to ambient atmosphere
- Removes ambient atmosphere's moisture from items entering the enclosure by purging or vacuum process

#### **Desiccation Ovens:**

• Subjects parts to Vacuum and baking to remove undissolved solvents which may outgas prior to seam welding



## HERMETIC SEALING CONTROLLED DRY ENVIRONMENT:

#### (E) Equipment – What is a glovebox purpose:



## HERMETIC SEALING CONTROLLED DRY ENVIRONMENT:

## **(E)** Equipment – Glovebox Images and Configurations



Compact enclosure with projection welder with gas purification system



Compact enclosure with seam welder



Modular glovebox with standalone gas analyzers and seam welder



Advanced glovebox with close looped analytical gas analyzers and unlimited oven bake schedules seam sealer and projection welder



Advanced glovebox with close looped analytical gas analyzers, unlimited oven bake schedules with multiple oven addon module and seam welder

## FUTURE OF HERMETIC SEALING PRODUCTS:

Robot assisted seam sealing pick and place systems



## SUMMARY

- Hermetic seam sealing of electronic packages
  - Parallel gap seam welding
  - Opposed electrode projection seam welding
- Hermetic seal testing
- What can go wrong with your process?
- Future of hermetic sealing products





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